

100 kPa On-Chip Temperature Compensated & Calibrated Silicon Pressure Sensors

The MPXM2102 device is a silicon piezoresistive pressure sensors providing a highly accurate and linear voltage output - directly proportional to the applied pressure. The sensor is a single, monolithic silicon diaphragm with the strain gauge and a thin-film resistor network integrated on-chip. The chip is laser trimmed for precise span and offset calibration and temperature compensation.

Features

- Temperature Compensated Over 0°C to +85°C
- Available in Easy-to-Use Tape & Reel
- Ratiometric to Supply Voltage
- Gauge Ported and Non Ported Options

Typical Applications

- Pump/Motor Controllers
- Robotics
- Level Indicators
- Medical Diagnostics
- Pressure Switching
- Barometers
- Altimeters

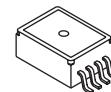
ORDERING INFORMATION

Device Type	Options	Case No.	MPX Series Order No.	Packing Options	Device Marking
Non-ported	Gauge	1320	MPXM2102D	Rails	MPXM2102D
	Gauge	1320	MPXM2102DT1	Tape & Reel	MPXM2102D
	Absolute	1320	MPXM2102A	Rails	MPXM2102A
	Absolute	1320	MPXM2102AT1	Tape & Reel	MPXM2102A
Ported	Gauge, Axial Port	1320A	MPXM2102GS	Rails	MPXM2102G
	Gauge, Axial Port	1320A	MPXM2102GST1	Tape & Reel	MPXM2102G
	Absolute, Axial Port	1320A	MPXM2102AS	Rails	MPXM2102A
	Absolute, Axial Port	1320A	MPXM2102AST1	Tape & Reel	MPXM2102A

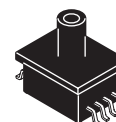
MPXM2102 SERIES

**COMPENSATED AND CALIBRATED
 PRESSURE SENSOR**
 0 TO 100 kPa (0 TO 14.5 psi)
 40 mV FULL SCALE SPAN
 (TYPICAL)

MPAK PACKAGES



MPXM2102D/A
CASE 1320-02



MPXM2102GS/AS
CASE 1320A-02

Pin Number

1	Gnd	3	V _S
2	+V _{out}	4	-V _{out}

Figure 1 shows a block diagram of the internal circuitry on the stand-alone pressure sensor chip.

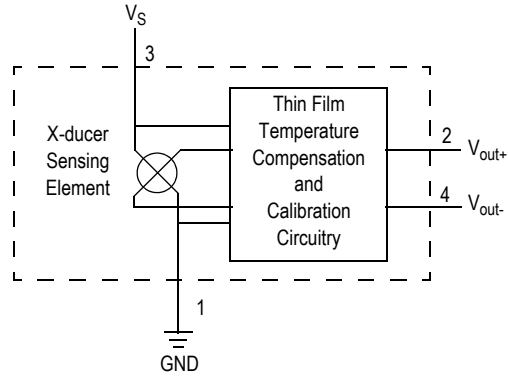


Figure 1. Temperature Compensated Pressure Sensor Schematic

**VOLTAGE OUTPUT VERSUS
APPLIED DIFFERENTIAL PRESSURE**

The differential voltage output of the sensor is directly proportional to the differential pressure applied.

The output voltage of the differential or gauge sensor increases with increasing pressure applied to the pressure side relative to the vacuum side. Similarly, output voltage increases as increasing vacuum is applied to the vacuum side relative to the pressure side.

Table 1. Maximum Ratings⁽¹⁾

Rating	Symbol	Value	Unit
Maximum Pressure	P_{max}	200	kPa
Storage Temperature	T_{stg}	-40 to +125	°C
Operating Temperature	T_A	-40 to +125	°C

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Table 2. Operating Characteristics ($V_S = 10$ Vdc, $T_A = 25^\circ\text{C}$.)

Characteristic	Symbol	Min	Typ	Max	Unit	
Pressure Range ⁽¹⁾	P_{OP}	0	—	100	kPa	
Supply Voltage ⁽²⁾	V_S	—	10	16	Vdc	
Supply Current	I_o	—	6.0	-	mAdc	
Full Scale Span ⁽³⁾	V_{FSS}	38.5	40	41.5	mV	
Offset ⁽⁴⁾	MPXM2102D/G Series MPXM2102A Series V_{off}	-1.0 -2.0	— —	1.0 2.0	mV	
Sensitivity	$\Delta V/\Delta P$	—	0.4	—	mV/kPa	
Linearity ⁽⁵⁾	MPXM2102D/G Series MPXM2102A Series	— —	-0.6 -1.0	— —	0.4 1.0	% V_{FSS}
Pressure Hysteresis ⁽⁵⁾ (0 to 100 kPa)	—	—	± 0.1	—	% V_{FSS}	
Temperature Hysteresis ⁽⁵⁾ (-40°C to +125°C)	—	—	± 0.5	—	% V_{FSS}	
Temperature Effect on Full Scale Span ⁽⁵⁾	TCV_{FSS}	-2.0	—	2.0	% V_{FSS}	
Temperature Effect on Offset ⁽⁵⁾	TCV_{off}	-1.0	—	1.0	mV	
Input Impedance	Z_{in}	1000	—	2500	Ω	
Output Impedance	Z_{out}	1400	—	3000	Ω	
Response Time ⁽⁶⁾ (10% to 90%)	t_R	—	1.0	—	ms	
Warm-Up	—	—	20	—	ms	
Offset Stability ⁽⁷⁾	—	—	± 0.5	—	% V_{FSS}	

1. 1.0 kPa (kiloPascal) equals 0.145 psi.

2. Device is ratiometric within this specified excitation range. Operating the device above the specified excitation range may induce additional error due to device self-heating.

3. Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.

4. Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.

5. Accuracy (error budget) consists of the following:

- Linearity: Output deviation from a straight line relationship with pressure, using end point method, over the specified pressure range.
- Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
- Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure, at 25°C.
- TcSpan: Output deviation at full rated pressure over the temperature range of 0 to 85°C, relative to 25°C.
- TcOffset: Output deviation with minimum rated pressure applied, over the temperature range of 0 to 85°C, relative to 25°C.

6. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.

7. Offset stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

LINEARITY

Linearity refers to how well a transducer's output follows the equation: $V_{out} = V_{off} + \text{sensitivity} \times P$ over the operating pressure range. There are two basic methods for calculating nonlinearity: (1) end point straight line fit (see Figure 2) or (2) a least squares best line fit. While a least squares fit gives the

“best case” linearity error (lower numerical value), the calculations required are burdensome.

Conversely, an end point fit will give the “worst case” error (often more desirable in error budget calculations) and the calculations are more straightforward for the user. The specified pressure sensor linearities are based on the end point straight line method measured at the midrange pressure.

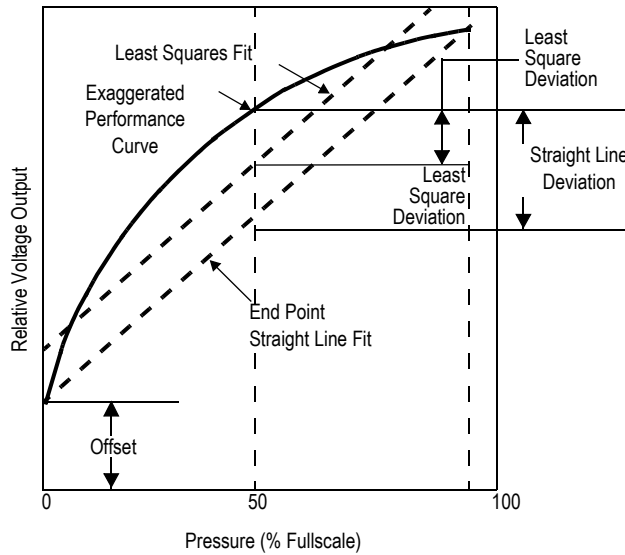


Figure 2. Linearity Specification Comparison

ON-CHIP TEMPERATURE COMPENSATION AND CALIBRATION

Figure 3 shows the minimum, maximum and typical output characteristics of the MPXM2120 series at 25°C. The output

is directly proportional to the differential pressure and is essentially a straight line.

A silicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm.

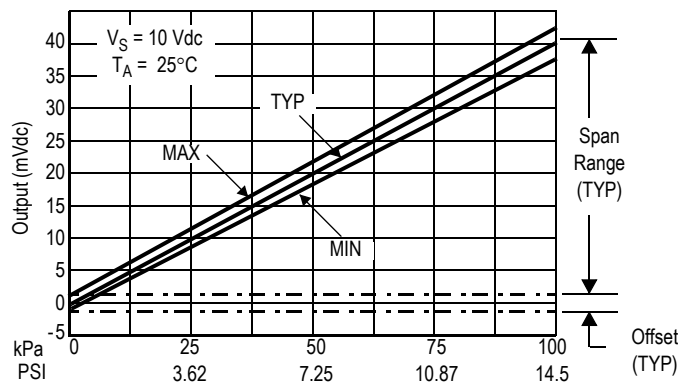
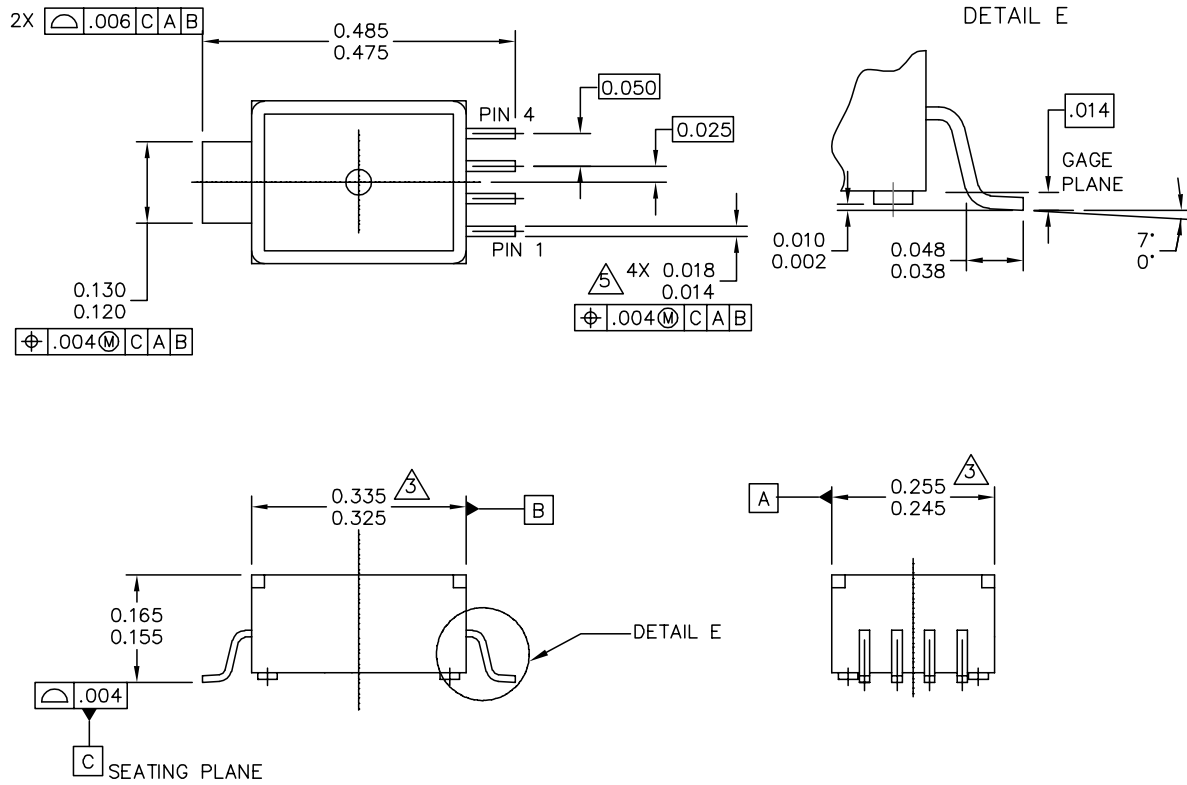


Figure 3. Output versus Pressure Differential

PACKAGE DIMENSIONS



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**CASE 1320-02
ISSUE B**

MPXM2102

PACKAGE DIMENSIONS

NOTES:

1. DIMENSIONS ARE IN INCHES.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. DIMENSION DOES NOT INCLUDE MOLD FLASH OR PROTRUSION. MOLD FLASH OR PROTRUSION SHALL NOT EXCEED .006" PER SIDE.

4. ALL VERTICAL SURFACES TO BE 5° MAXIMUM.

5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 MAXIMUM.

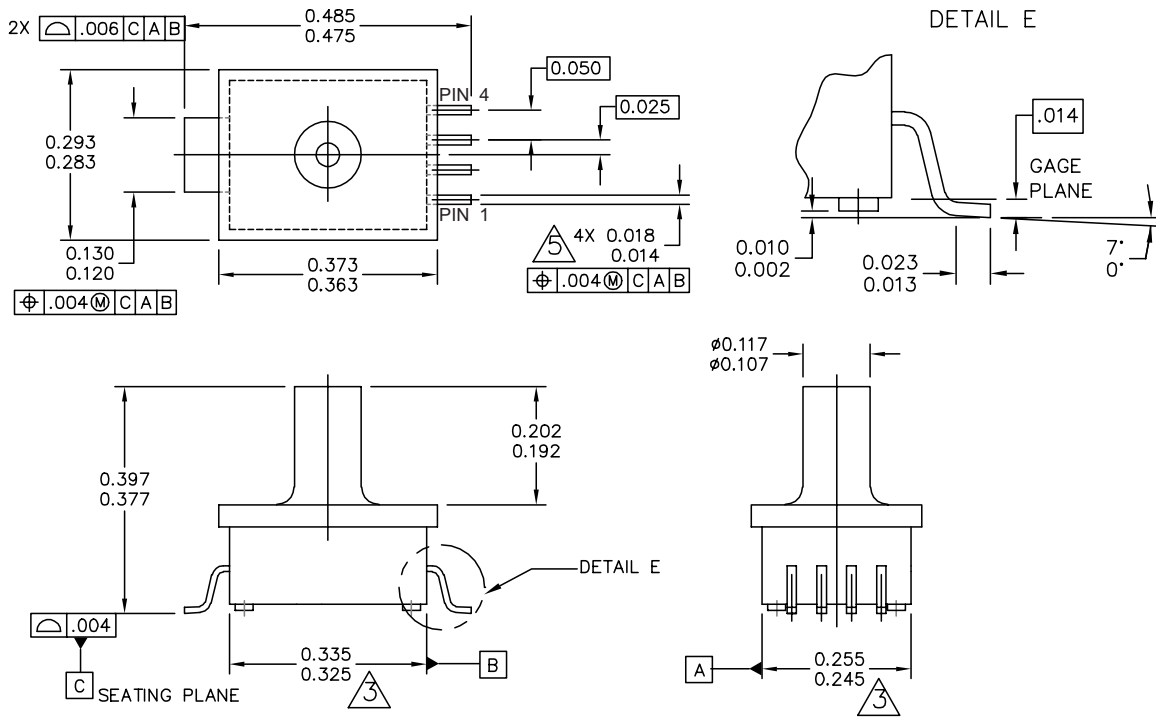
PIN 1: GND
 PIN 2: +Vout
 PIN 3: Vs
 PIN 4: -Vout

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**CASE 1320-02
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**CASE 1320A-02
ISSUE A**

MPXM2102

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ISSUE A**

How to Reach Us:

Home Page:

www.freescale.com

E-mail:

support@freescale.com

USA/Europe or Locations Not Listed:

Freescale Semiconductor
Technical Information Center, CH370
1300 N. Alma School Road
Chandler, Arizona 85224
+1-800-521-6274 or +1-480-768-2130
support@freescale.com

Europe, Middle East, and Africa:

Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7
81829 Muenchen, Germany
+44 1296 380 456 (English)
+46 8 52200080 (English)
+49 89 92103 559 (German)
+33 1 69 35 48 48 (French)
support@freescale.com

Japan:

Freescale Semiconductor Japan Ltd.
Headquarters
ARCO Tower 15F
1-8-1, Shimo-Meguro, Meguro-ku,
Tokyo 153-0064
Japan
0120 191014 or +81 3 5437 9125
support.japan@freescale.com

Asia/Pacific:

Freescale Semiconductor Hong Kong Ltd.
Technical Information Center
2 Dai King Street
Tai Po Industrial Estate
Tai Po, N.T., Hong Kong
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